CLR® has excellent printability. In order to increase joint reliability, even with thicker stencil, enough solder paste can be printed for fine pitch.

**Characteristics**

- To improve printability, new synthetic resin with enhanced water repellancy is developed
- With mask thickness 150μm, stable printing is possible for 0.4mmQFP & 0.5mmBGA
- Excellent printability is achieved even at high speed printing (~100mm/sec)
- Resistance to flux residue crack (~-40°125°C, 2,000 cycle)

**Printability**

**Mechanism for improved printing performance**

- Less friction with metal mask opening, and as a result, fine pitch printing improved
- Adding water repellant material improved electrical reliability

**Printing**

- 0.4mmQFP · 0.5mmBGA mounting is possible with 150μm mask
- 0.4mm Pitch QFP
- 0.5mm Pitch BGA

**High Speed Printing**

- Maintain excellent printing at high speed printing (100mm/sec)